

**Fast Acting | 0.126x0.064 inch
Thick Film Chip Fuses**

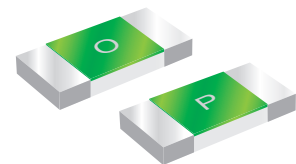
1206FA-xxxD Series



1206FA-xxxD Series are the fuses set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.

Features

- High inrush current withstanding capability
- AEC-Q200 Automotive Grade Certified
- Compatible with reflow and wave solder
- Ceramic and glass construction Excellent environmental integrity
- One time positive disconnect
- Lead Free and Halogen free material



Applications

- Flat panel displays and televisions
- Automotive infotainment and ECU
- Computer servers
- Portable electronics
- Mobile device chargers
- Power Battery Packs

Electrical Characteristics

| Amp Rating | % of Amp Rating | Opening Time |
|------------|-----------------|----------------|
| 20~30A | 100% | 4 Hours Min. |
| 20~30A | 350% | 5 Seconds Max. |
| 20~30A | 1000% | 0.2ms~20ms |

Specification

| Part Number | Ampere Rating (A) | Voltage Rating | Interrupting Rating | Typical Cold Resistance (Ohms) | Typical Melting I ² t (A ² Sec) | Typical Voltage Drop (V) | Marking Code |
|-------------|-------------------|----------------|---------------------|--------------------------------|---|--------------------------|--------------|
| 1206FA-20AD | 20.0 | 32Vdc @ 150A | | 0.0034 | 45 | 0.080 | Q |
| 1206FA-25AD | 25.0 | | | 0.0016 | 54 | 0.090 | L |
| 1206FA-30AD | 30.0 | 24Vdc @ 300A | | 0.0013 | 90 | 0.090 | Z |

- DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)
- DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25 C
- Typical Pre-arcing I²t are measured at 10In Current
- Choice fuse for surge application (USB charger etc.), make sure the I²t of fuse is 4 times than surge.
- Specifications are subject to change without notice. Application testing is strongly recommended.

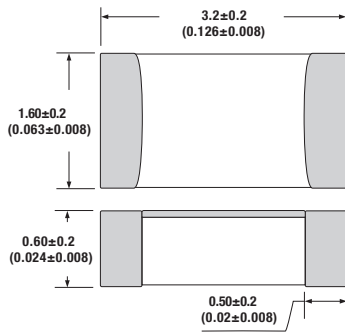
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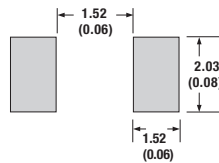
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Dimension

Unit: mm/inch



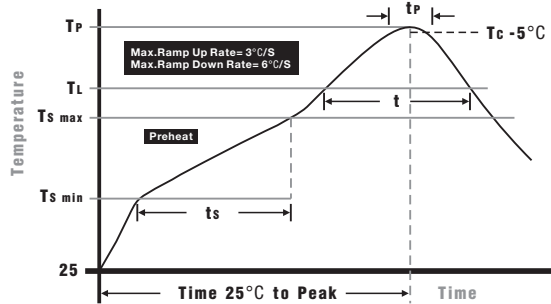
Pad layout



Packaging

- Quantity: 3,000pcs
- 8mm wide tape on 178mm(7 inch) diameter reel -specification EIA Standard 481.

Soldering Parameters

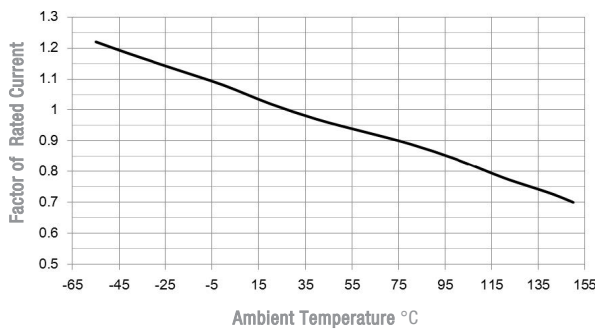


Wave Soldering: 260°C, 10 seconds max.
Infrared Reflow: 260°C, 30 seconds max.

IR Reflow Profile

| | |
|--|------------------|
| Preheat Heat | |
| Temperature min (T_{smin}) | 150°C |
| Temperature max (T_{smax}) | 200°C |
| Time (T_{smin} to T_{smax}) (t_s) | 60 -120 seconds |
| Average ramp-up rate (T_{smax} to T_p) | 3°C/second max. |
| Liquidous temperature (T_l) | 217°C |
| Time at liquidous (t_l) | 60 - 150 seconds |
| Peak temperature(T_p) | 260+0/-5°C |
| Time within 5°C of actual peak Temperature (t_p) | 10 - 30 seconds |
| Average ramp-down rate (T_p to T_{smax}) | 6°C/second max. |
| Time 25 °C to peak temperature | 8 minutes max. |

Temperature Derating Curve



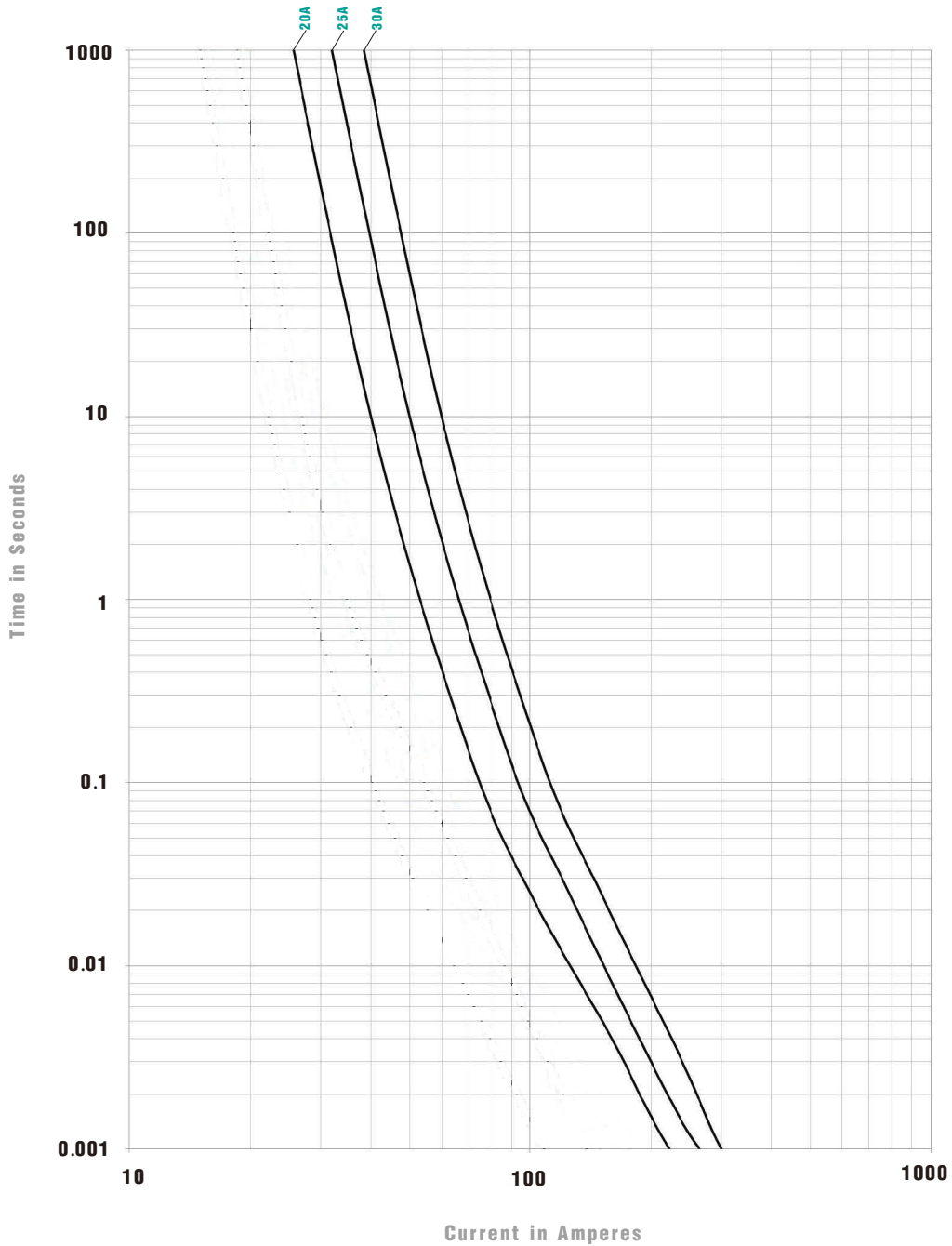
- Normal ambient temperature: 23+/-3°C
- Operating temperature: -55 ~ 150 C , with proper correction factor applied

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Average Time Current Curves



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